

## Session Program

29 June 2026 to 3 July 2026



## 5th DRD3 week on Solid State Detectors R&D

### ***WG7 (WP4)***

Institute of Space Science & National Institute of Materials Physics  
National Institute of Statistics

# Tuesday 30 June

16:00

## WG7 (WP4)

**Session** |

**Location:** Institute of Space Science & National Institute of Materials Physics, National Institute of Statistics

16:00–16:05 **Introduction**

**Speakers**

Dominik Dannheim, Fabian Huegging, Giovanni Calderini

16:05–16:25 **In-house Flip-Chip Hybridisation Updates**

**Speaker**

Dr Ahmet Lale

16:25–16:40

**First results from irradiation tests of ACA-bonded chain devices (t.b.c.)**

16:40–17:00 **First preliminary results on bonding activities at INFN Cagliari**

**Speaker**

Angelo Loi

17:00–17:20

**In-house indium bumping and bonding for fine-pitch hybrid pixel detector R&D**

**Speaker**

Mateus Vicente

17:20–17:40

**Nanowire-Based Thermal Interconnects for Enhanced Thermal Management in High-Density Silicon Pixel Modules**

**Speaker**

Julian Weick

17:40–18:00 **All-Silicon Modules - RDL layers for thin CMOS chips**

**Speaker**

Andreas Ulm

18:00